

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 11-168150

(43)Date of publication of application : 22.06.1999

(51)Int.Cl.

H01L 23/12

H01L 25/10

H01L 25/11

H01L 25/18

(21)Application number : 09-334492

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(22)Date of filing : 04.12.1997

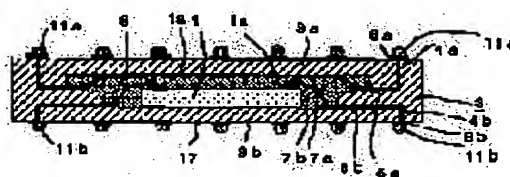
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## (54) SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

## (57)Abstract:

**PROBLEM TO BE SOLVED:** To increase the distance between terminals and to enhance the reliability of a semiconductor integrated circuit device at mounting of the device on a printed wiring board or the like, by a method wherein the device is constituted of a plurality of the external terminals, which are provided on external connection pads and consist of a conductive material.

**SOLUTION:** Wiring parts 5a and 5b are installed in alignment with each other in two steps on an insulating base material 3, and the parts 5a and 5b are respectively connected with external connection pads 6a and 6b via through-holes 4a and 4b. At this time, bonding wires 7a and 7b are alternately connected with conductive pads 1a and the wiring parts 5a and 5b installed in the two steps. Through such wirings, the pads 1a arranged in a high density on a semiconductor chip can be made to have spaces having a considerable margin in the parts 5a and 5b. Moreover, since the pads 6a and 6b and external connection terminals 11a and 11b are provided in two surfaces, the interval between the terminals can be taken widely, and when a semiconductor integrated circuit device is mounted on a printed wiring board or the like, the reliability of the device for soldering bridges or the like is improved. Moreover, the structure of a package may be constituted in small size.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision  
of rejection]

[Date of requesting appeal against examiner's  
decision of rejection]

[Date of extinction of right]

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